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## Product Change Notification - JAON-08QUPF367 [\(Printer Friendly\)](#)

**Date:** 12 Oct 2015

**Notification subject:** CCB 1641.01 Final Notice: Qualification of new lead frame design (dimple) in selected products available in 8L DFN (2x3x0.9 mm) package using Gold (Au) bond wire at NSEB assembly site.

**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of new lead frame design (dimple) in selected products available in 8L DFN (2x3x0.9 mm) package using Gold (Au) bond wire at NSEB assembly site.

**Pre Change:**

Lead frame design (U-groove)

**Post Change:**

New lead frame design (dimple)

**Impacts to Data Sheet:**

None

**Reason for Change:**

To improve manufacturability and qualify new lead frame design (dimple).

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

November 09, 2015 (date code: 1546)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Markings to Distinguish Revised from Unrevised Devices:**

Traceability code

**Revision History:**

**June 29, 2015:** Issued initial notification.

**October 12, 2015:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from August 20, 2015 to November 9, 2015.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-08QUPF367\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-08QUPF367\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-08QUPF367\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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